LNJ115W88RA

Surface Mounting Chip LED

TSS-2 Type

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Yellow Green						
Parameter	Symbol	Rating	Unit			
Power dissipation	P _D	60	mW			
Forward current	$I_{\rm F}$	20	mA			
Pulse forward current *	I_{FP}	60	mA			
Reverse voltage	V _R	4	V			
Operating ambient temperature	T _{opr}	-30 to +85	°C			
Storage temperature	T _{stg}	-40 to +100	°C			

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

• Amber

Parameter	Symbol	Rating	Unit	
Power dissipation	P _D	55	mW	
Forward current	I _F	20	mA	
Pulse forward current *	I _{FP}	60	mA	
Reverse voltage	V _R	4	V	
Operating ambient temperature	T _{opr}	-30 to +80	°C	
Storage temperature	T _{stg}	-40 to +100	°C	

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

Electro-Optical Characteristics $T_a = 25^{\circ}C$

• Yellow G	reen
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Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	I _O	$I_F = 10 \text{ mA}$	1.8	5.0		mcd
Reverse current	I _R	$V_R = 4 V$			10	μΑ
Forward voltage	V _F	$I_{\rm F} = 10 {\rm mA}$		2.03	2.6	V
Peak emission wavelength	$\lambda_{\rm P}$	$I_{\rm F} = 10 {\rm mA}$		565		nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$		30		nm

Lighting ColorYellow Green

• Amber

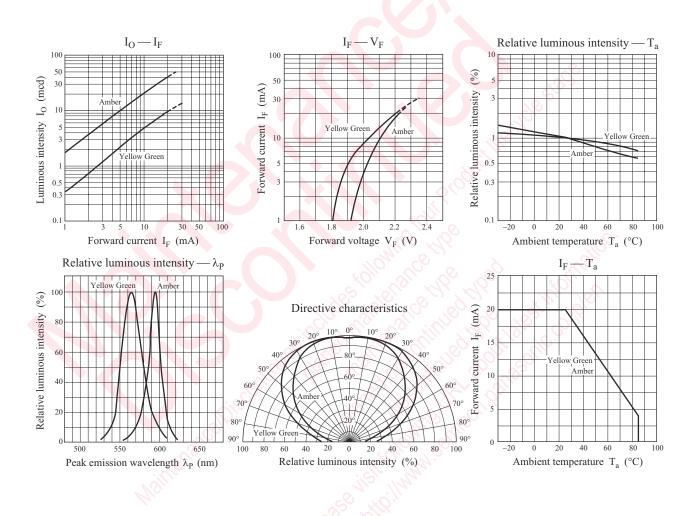
LNJ115W88RA

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Electro-Optical Characteristics (Continued) $T_a = 25^{\circ}C$

• Amber

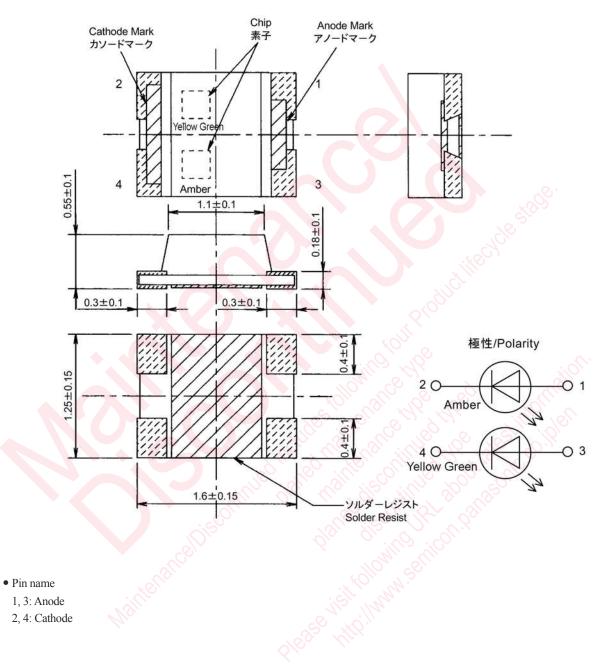
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	I _O	$I_F = 10 \text{ mA}$	7	21		mcd
Reverse current	I _R	$V_R = 4 V$			100	μΑ
Forward voltage	$V_{\rm F}$	$I_{\rm F} = 10 \ {\rm mA}$		2.1	2.6	V
Peak emission wavelength	$\lambda_{\rm P}$	$I_{\rm F} = 10 {\rm mA}$		595		nm
Spectral half band width	Δλ	$I_{\rm F} = 10 \ {\rm mA}$		15		nm



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Package (Unit: mm)

KLTFTN4K1540



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